

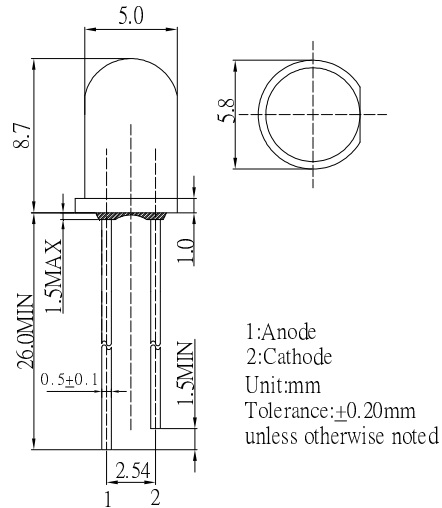
■ **Features**

- High Radiant Power LEDs
- 5mm Standard Directivity
- UV Resistant Epoxy
- Water Clear Type

■ **Applications**

- IrDA
- Encoder
- Data Communication
- IR camera

■ **Outline Dimension**

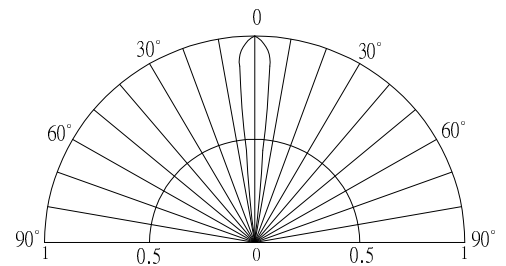


■ **Absolute Maximum Rating (Ta=25°C)**

Item	Symbol	Value	Unit
DC Forward Current	I <sub>F</sub>	70	mA
Pulse Forward Current*	I <sub>FP</sub>	700	mA
Reverse Voltage	V <sub>R</sub>	5	V
Power Dissipation	P <sub>D</sub>	126	mW
Operating Temperature	T <sub>opr</sub>	-30 ~ +85	°C
Storage Temperature	T <sub>stg</sub>	-40 ~ +100	°C
Lead Soldering Temperature	T <sub>sol</sub>	260°C/5sec	-

\*Pulse width Max.10ms Duty ratio max 1/10

■ **Directivity**



■ **Electrical -Optical Characteristics (Ta=25°C)**

Item	Symbol	Condition	Min.	Typ.	Max.	Unit
DC Forward Voltage	V <sub>F</sub>	I <sub>F</sub> =50mA	-	1.6	1.8	V
DC Reverse Current	I <sub>R</sub>	V <sub>R</sub> =5V	-	-	10	μA
Peak Wavelength	λ <sub>p</sub>	I <sub>F</sub> =50mA	-	850	-	nm
Radiant Intensity	I <sub>e</sub>	I <sub>F</sub> =50mA	150	220	330	mW/Sr
Radiant Power	P <sub>o</sub>	I <sub>F</sub> =50mA	15	30	45	mW
50% Power Angle	2θ <sub>1/2</sub>	I <sub>F</sub> =50mA	-	15	-	deg

\*1 Tolerance of measurements of Peak wavelength is ±1nm

\*2 Tolerance of measurements of Radiant Power is ±15%

\*3 Tolerance of measurements of forward voltage is ±0.1V

## LAMP APPLICATION (PB FREE SOLDERJING)

Apply to LAMP (DIP) SERIES.

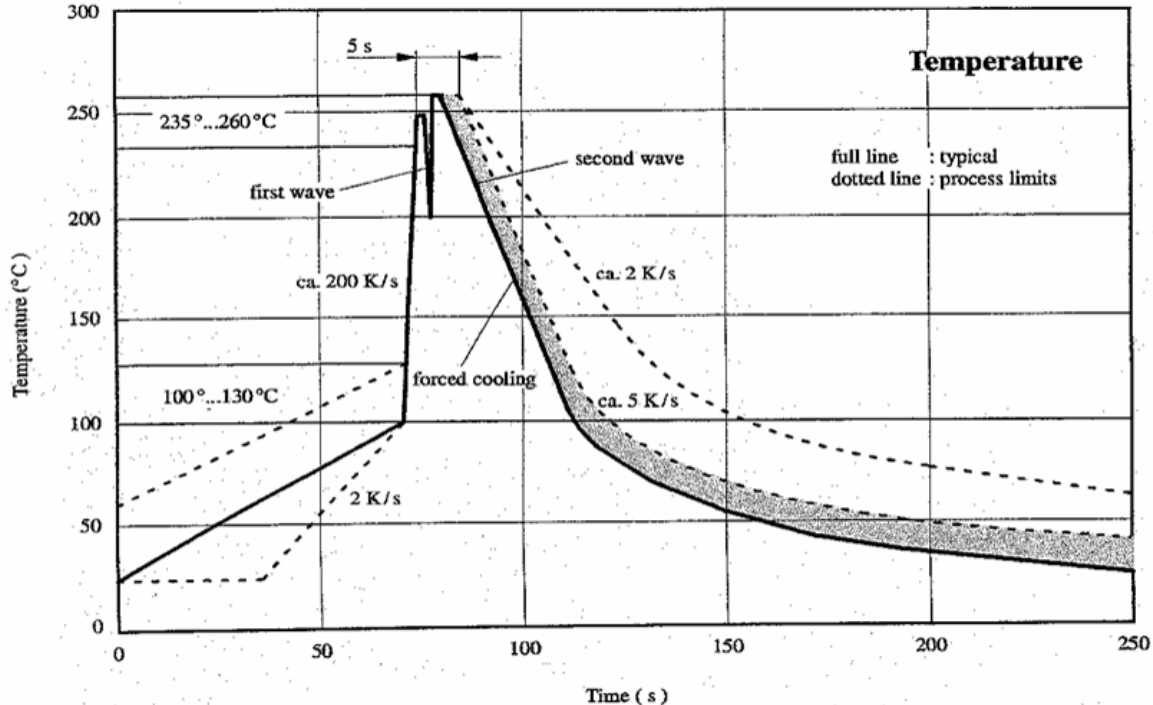
### Description:

#### (1) Manual soldering (Solder Iron)

- (1.1) Temperature at tip of the iron: 350°C Max.
- (1.2) It's banned to load any stress on the resin during soldering.
- (1.3) Soldering time: 3sec.Max.(one time only.)
- (1.4) Leave 3mm of minimum distance from the base of the epoxy.

#### (2) Dip Soldering (Wave Soldering-Solder Bath)

- (2.1) Leave 3mm of minimum distance from the base of the epoxy.  
Soldering beyond the base of the tie bar (stand off) is recommended.
- (2.2) When soldering, do not put stress on the LEDs during heating.
- (2.3) Cutting the lead frames at high temperatures may cause LED failure.
- (2.4) Never take next process until the component is cooled down to room temperature after reflow.
- (2.5) After soldering, do not warp the circuit board.
- (2.6) The recommended dip soldering profile is the following.



Wave soldering of double wave optodevices